

16-Channel Constant Current LED Sink Driver

Features

- 16 constant-current output channels
- Constant output current invariant to load voltage change: Constant output current range:

1-45mA@V_{DD}=5V;

1-30mA@V_{DD}=3.3V

- Excellent output current accuracy (I_{OUT} =25mA@V_{DS}=0.7V): between channels: ±1.5% (typ.) and ±2% (max.) between ICs: ±1.5% (typ.) and ±3% (max.)
- Output current adjusted through an external resistor
- Fast response of output current, \overline{OE} (min.): 70ns with good uniformity between output channels
- Staggered delay of output
- 25MHz clock frequency
- Schmitt trigger input
- 3.3V/ 5V supply voltage
- RoHS compliant package

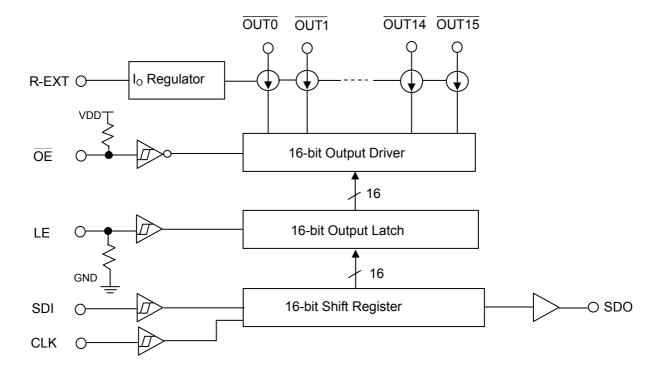


Product Description

With PrecisionDriveTM technology, MBI5025 is designed for LED displays which require to operate at low current and to match the luminous intensity of each channel. It provides supply voltage and accepts CMOS logic input at 3.3V and 5.0V to meet the trend of low power consumption. MBI5025 contains a serial buffer and data latches which convert serial input data into parallel output format. At MBI5025 output stage, sixteen regulated current ports are designed to provide uniform and constant current sinks for driving LEDs within a large range of V_F variations.

MBI5025 provides users with great flexibility and device performance while using MBI5025 in their system design for LED display applications, e.g. LED panels. It accepts an input voltage range from 3V to 5.5V and maintains a constant current up from 1mA to 45mA determined by an external resistor, R_{ext} , which gives users flexibility in controlling the light intensity of LEDs. MBI5025 guarantees to endure maximum 17V at the output port. The high clock frequency, 25 MHz, also satisfies the system requirements of high volume data transmission.

Block Diagram



Terminal Description

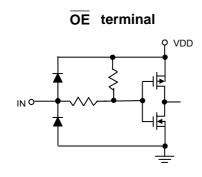
Pin No.	Pin Name	Function
1	GND	Ground terminal for control logic and current sink
2	SDI	Serial-data input to the shift register
3	CLK	Clock input terminal for data shift on rising edge
		Data strobe input terminal
4	LE	Serial data is transferred to the output latch when LE is high. The data is latched when LE goes low.
5~20	$\overline{OUT0} \sim \overline{OUT15}$	Constant current output terminals
21	ŌĒ	Output enable terminal When (active) low, the output drivers are enabled; when high, all output drivers are turned OFF (blanked).
22	SDO	Serial-data output to the following SDI of next driver IC. SDO signal change on rising edge of CLK.
23	R-EXT	Input terminal used to connect an external resistor for setting up output current for all output channels
24	VDD	3.3V/5V supply voltage terminal

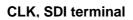
Pin Configuration

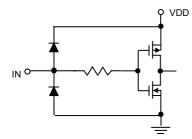
			1
GND	1	⊔ ₂₄	VDD
SDI	2	23	R-EXT
CLK	3	22	SDO
LE 🛛	4	21	OE
OUT0	5	20	OUT15
OUT1	6	19	OUT14
OUT2	7	18	OUT13
OUT3	8	17	OUT12
OUT4	9	16	OUT11
OUT5	10	15	OUT10
OUT6	11	14	OUT9
OUT7	12	13	OUT8

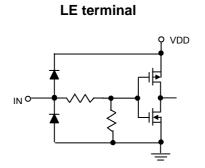
MBI5025GD/GF/GP/GTS

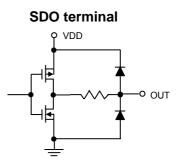
Equivalent Circuits of Inputs and Outputs



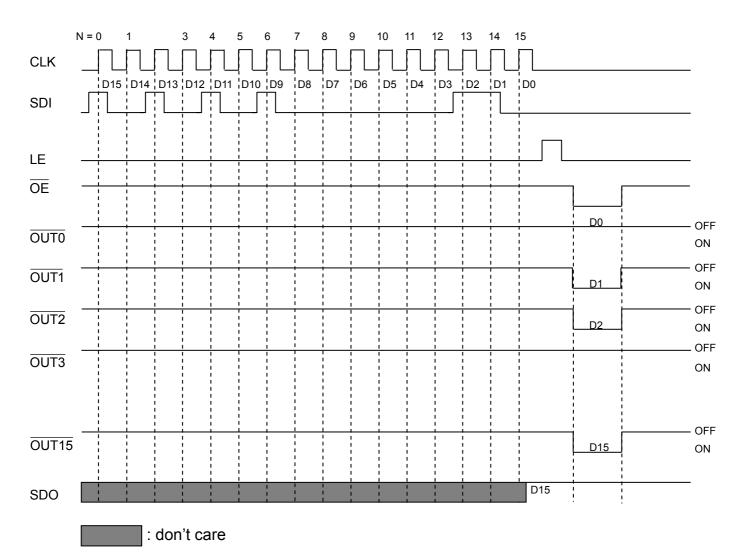








Timing Diagram



Truth Table

CLK	LE	ŌĒ	SDI	OUT0 OUT 7 OUT15	SDO
	Н	L	D _n	Dn Dn - 7Dn - 15	D _{n-15}
	L	L	D _{n+1}	No Change	D _{n-14}
	Н	L	D _{n+2}	$\overline{Dn+2}$ $\overline{Dn-5}$ $\overline{Dn-13}$	D _{n-13}
	х	L	D _{n+3}	$\overline{Dn+2} \dots \overline{Dn-5} \dots \overline{Dn-13}$	D _{n-13}
—	х	Н	D _{n+4}	Off	D _{n-13}

Maximum Ratings

Charact	eristic	Symbol	Rating	Unit
Supply Voltage		V _{DD}	0~7.0	V
Input Voltage		V _{IN}	-0.4~V _{DD} +0.4	V
Output Current		Ι _{ουτ}	+90	mA
Sustaining Voltage at OUT	Port	V _{DS}	-0.5~+17.0	V
GND Terminal Current		I _{GND}	+1000	mA
	GD-type		2.88	
Power Dissipation	GF-type	_	2.35	10/
(On PCB, Ta=25°C)	GP-type	– P _D	1.76	W
	GTS-type		3.87	
	GD-type		46.60	
Thermal Resistance	GF-type		53.28	°C 111
(On PCB, Ta=25°C)	GP-type	- R _{th(j-a)}	70.90	°C/W
	GTS-type		32.34	
Operating Temperature		T _{opr}	-40~+85	°C
Storage Temperature		T _{stg}	-55~+150	°C

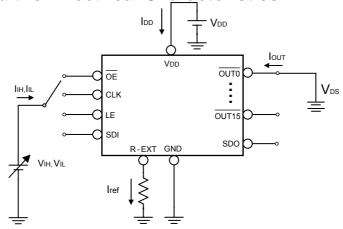
Electrical Characteristics (V_{DD} = 5.0V)

Characteristics		Symbol	Cone	dition	Min.	Тур.	Max.	Unit
Supply Voltag	e	V _{DD}		-	4.5	5.0	5.5	V
Sustaining Vo Ports	tage at OUT	V _{DS}	OUT0~OUT15		-	-	17.0	V
		I _{OUT}	Refer to "Test Cil Characteristics"	rcuit for Electrical	1	-	45	mA
Output Current		I _{ОН}	SDO		-	-	-1.0	mA
		I _{OL}	SDO		-	-	1.0	mA
Innut Valtaga	"H" level	V _{IH}	Ta =-40~85°C		0.7*V _{DD}	-	V _{DD}	V
Input Voltage	"L" level	V _{IL}	Ta =-40~85°C		GND	-	0.3*V _{DD}	V
Output Leakag	e Current	I _{ОН}	V _{DS} =17.0V		-	-	0.5	μA
Output Voltage	SDO	V _{OL}	I _{OL} =+1.0mA		-	-	0.4	V
Oulput voltage	300	V _{OH}	I _{OH} =-1.0mA		4.6	-	-	V
Output Current	1	I _{OUT1}	V _{DS} =1.0V	R _{ext} =18kΩ	-	1.0	-	mA
Current Skew	Current Skew dI_{OUT1} $I_{OL}=1mA_{V_{DS}}$ $R_{ext}=18k\Omega$		R _{ext} =18kΩ	-	±1.5	±3.0	%	
Output Current	2	I _{OUT2}	V _{DS} =1.0V	R _{ext} =720Ω	-	25.8	-	mA
Current Skew		dl _{out2}	I _{OL} =25.8mA V _{DS} =1.0V	R _{ext} =720Ω	-	±1.5	±2.0	%
Output Current Output Voltage		%/dV _{DS}	V _{DS} within 1.0V and 3.0V		-	±0.1	-	%/V
Output Current Supply Voltage	VS.	$\%/dV_{DD}$	V_{DD} within 4.5V and 5.5V		-	-	±1.0	%/V
Pull-up Resisto	r	R _{IN} (up)	ŌĒ		250	500	800	KΩ
Pull-down Res	Pull-down Resistor		LE		250	500	800	KΩ
		I _{DD} (off) 1	R _{ext} =Open, OUT0 ~ OUT15 =Off		-	2.4	5.0	
	"OFF"	I _{DD} (off) 2	R _{ext} =1860Ω, <u>OU</u>	TO ~ OUT15 =Off	-	4.3	7.0	
Supply Current		I _{DD} (off) 3		0UT15 = Off	-	5.7	9.0	mA
	"ON"	I _{DD} (on) 1		T0 ~ OUT15 =On	-	4.6	8.5	
	"ON"	I _{DD} (on) 2	R _{ext} =744Ω, <u>ου</u> τ	<u></u>	-	6.0	9.5	

Electrical Characteristics (V_{DD}= 3.3V)

Characteristics		Symbol	Con	dition	Min.	Тур.	Max.	Unit
Supply Voltage	e	V _{DD}		-	3.0	3.3	4.5	V
Sustaining Vol Ports	tage at OUT	V _{DS}		5	-	-	17.0	V
		Ι _{ουτ}	Refer to "Test Ci Characteristics"	ircuit for Electrical	1	-	30	mA
Output Current		I _{OH}	SDO		-	-	-1.0	mA
		I _{OL}	SDO		-	-	1.0	mA
Innut \/altaga	"H" level	V _{IH}	Ta=-40~85°C		0.7*V _{DD}	-	V _{DD}	V
Input Voltage	"L" level	V _{IL}	Ta=-40~85°C		GND	-	0.3*V _{DD}	V
Output Leakag	e Current	I _{он}	V _{DS} =17.0V		-	-	0.5	μA
	800	V _{OL}	I _{OL} =+1.0mA		-	-	0.4	V
Output Voltage	SDO	V _{OH}	I _{OH} =-1.0mA		2.9	-	-	V
Output Current	1	I _{OUT1}	V _{DS} =1.0V	R _{ext} =18kΩ	-	1.0	-	mA
Current Skew	Skew dI_{OUT1} $I_{OL}=1mA$ $R_{ext}=18k\Omega$		-	±1.5	±3.0	%		
Output Current	2	I _{OUT2}	V _{DS} =1.0V	R _{ext} =720Ω	-	25.8	-	mA
Current Skew		dl _{out2}	$I_{OL}=25.8\text{mA}$ $V_{DS}=1.0\text{V}$ $R_{ext}=720\Omega$		-	±1.5	±2.0	%
Output Current Output Voltage		%/dV _{DS}	V_{DS} within 1.0V a	and 3.0V	-	±0.1	-	%/V
Output Current Supply Voltage		%/dV _{DD}	V_{DD} within 3.0V a	and 4.5V	-	-	±1.0	%/V
Pull-up Resisto	r	R _{IN} (up)	ŌĒ		250	500	800	KΩ
Pull-down Resistor		R _{IN} (down)			250	500	800	KΩ
		I _{DD} (off) 1	R _{ext} =Open, OU	T0 ~ OUT15 =Off	-	1.8	5.0	
	"OFF"	I _{DD} (off) 2	R _{ext} =6200Ω, Ο υ	T0 ~ OUT15 =Off	-	4.0	7.0	
Supply Current		I _{DD} (off) 3		T0 ~ OUT15 =Off	-	5.2	8.5	mA
	" 2 1 1	I _{DD} (on) 1		T0 ~ OUT15 =On	-	4.5	7.0	
	"ON"	I _{DD} (on) 2	$R_{ext}=744\Omega, \overline{OU}$	T0 ~ OUT15 =On	-	5.5	8.5	

Test Circuit for Electrical Characteristics



Switching Characteristics (V_{DD}= 5.0V)

Character	Characteristics		Condition	Min.	Тур.	Max.	Unit
	CLK-OUT2n	+		-	50	70	ns
	CLK-OUT2n+1	t _{pLH1}		-	35	55	ns
	LE-OUT2n			-	50	70	ns
Propagation Delay Time ("L" to "H")	$LE-\overline{OUT2n+1}$	t _{pLH2}		-	35	55	ns
· · · ·	OE - OUT2n			-	50	70	ns
	\overline{OE} - $\overline{OUT2n + 1}$	t _{pLH3}		-	35	55	ns
	CLK-SDO	t _{pLH}		-	20	40	ns
	CLK-OUT2n			-	90	110	ns
	CLK-OUT2n+1	t _{pHL1}		-	75	95	ns
	LE-OUT2n			-	90	110	ns
Propagation Delay Time ("H" to "L")	$LE-\overline{OUT2n+1}$	t _{pHL2}	$V_{DD}=5.0 V \\ V_{DS}=1.0 V \\ V_{IH}=V_{DD} \\ V_{IL}=GND \\ R_{ext}=930 \Omega \\ V_{L}=4.5 V \\ R_{L}=162 \Omega \\ C_{L}=10 \text{ pF}$	-	75	95	ns
	OE - OUT2n	t _{pHL3}		-	90	110	ns
	\overline{OE} - $\overline{OUT2n + 1}$			-	75	95	ns
	CLK-SDO	t _{pHL}		-	20	40	ns
	CLK	t _{w(CLK)}		20	-	-	ns
Pulse Width	LE	t _{w(L)}		20	-	-	ns
	ŌE	t _{w(OE)}		70	100	-	ns
Hold Time for LE		t _{h(L)}		30	-	-	ns
Setup Time for LE		t _{su(L)}		5	-	-	ns
Hold Time for SDI		t _{h(D)}		5	-	-	ns
Setup Time for SDI		t _{su(D)}		3	-	-	ns
Maximum CLK Rise Time		t _r		-	-	500	ns
Maximum CLK Fall Time		t _f		-	-	500	ns
SDO Rise Time		t _{r,SDO}		-	10	-	ns
SDO Fall Time		t _{f,SDO}		-	10	-	ns
Output Rise Time of Outp	ut Ports	t _{or}		-	40	-	ns
Output Fall Time of Outpu	t Ports	t _{of}		-	55	-	ns

* Among output channels exist 15ns delay time between odd number $\overline{OUT2n+1}$ (e.g.:Bit1/Bit3/Bit5...)and even number $\overline{OUT2n}$ (ex: Bit0/Bit2/Bit4...). MBI5025 has a built-in staggered circuit to perform delay mechanism, by which the even and odd output ports will be turned on at a different time so that the instant current from the power line will be lowered.

Setup Time for SDI

SDO Rise Time

SDO Fall Time

Maximum CLK Rise Time

Maximum CLK Fall Time

Output Rise Time of Output Ports

Output Fall Time of Output Ports

16-Channel Constant Current LED Sink Driver

3

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10

10

40

60

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500

500

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-

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Unit

ns

Switching Characteristics (V_{DD}= 3.3V) Symbol Condition **Characteristics** Min. Тур. Max. 70 50 _ CLK-OUT2n t_{pLH1} 35 55 CLK-OUT2n+1 70 50 _ LE-OUT2n t_{pLH2} Propagation Delay Time 55 35 LE-OUT2n+1 _ ("L" to "H") 50 70 OE - OUT2n t_{pLH3} 35 55 \overline{OE} - $\overline{OUT2n + 1}$ CLK-SDO 20 40 t_{pLH} _ 115 135 _ CLK-OUT2n t_{pHL1} 100 120 CLK-OUT2n+1115 135 LE-OUT2n _ t_{pHL2} Propagation Delay Time 100 120 LE-OUT2n+1_ ("H" to "L") V_{DD}=3.3 V V_{DS}=1.0 V 105 _ 125 OE - OUT2n V_{IH}=V_{DD} t_{pHL3} 90 110 \overline{OE} - $\overline{OUT2n + 1}$ V_{IL}=GND _ R_{ext}=930 Ω CLK-SDO 20 40 _ t_{pHL} V₁=4.5 V CLK $R_1 = 162 \Omega$ 20 _ _ t_{w(CLK)} C_L=10 pF 20 Pulse Width _ _ LE t_{w(L)} 100 130 t_{w(OE)} _ OE Hold Time for LE 30 _ _ t_{h(L)} Setup Time for LE 5 _ _ t_{su(L)} Hold Time for SDI 5 t_{h(D)} -_

t_{su(D)}

tr

tf

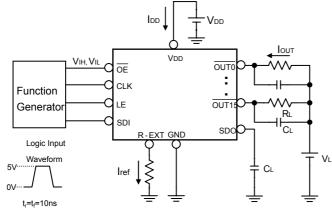
t_{r.SDO}

t_{f,SDO}

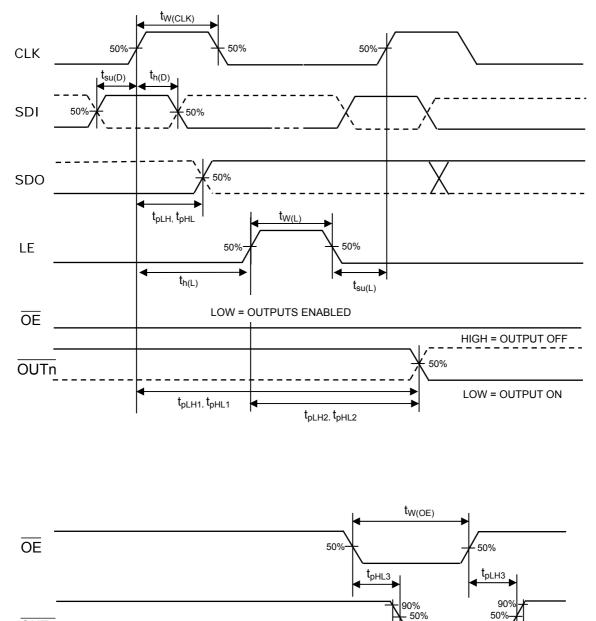
tor

tof

Test Circuit for Switching Characteristics



Timing Waveform



50%

t₋

%

10%

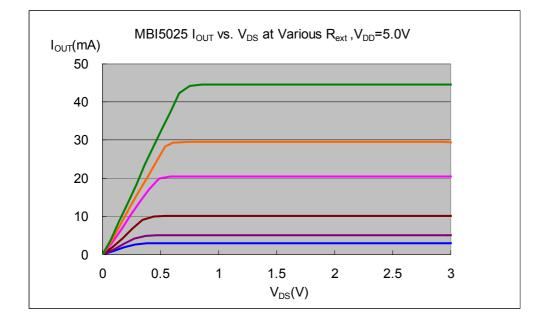
tof

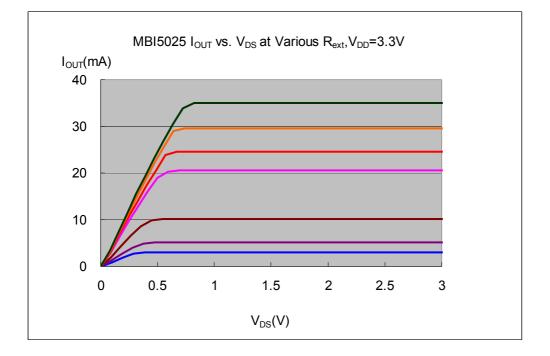
Application Information

Constant Current

To design LED displays, MBI5025 provides nearly no variations in current from channel to channel and from IC to IC. This can be achieved by:

- 1) The maximum current variation between channels is less than $\pm 2\%$, and that between ICs is less than $\pm 3\%$.
- 2) In addition, the current characteristic of output stage is flat and users can refer to the figure as shown below. The output current can be kept constant regardless of the variations of LED forward voltages (V_F). This performs as a perfection of load regulation.



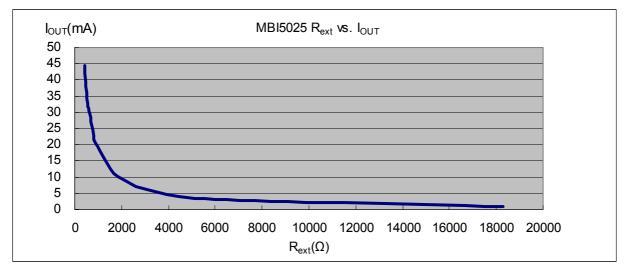


Adjusting Output Current

The output current of each channel (I_{OUT}) is set by an external resistor, R_{ext} . The relationship between I_{OUT} and R_{ext} is shown in the following figure.

Also, the output current can be calculated from the equation:

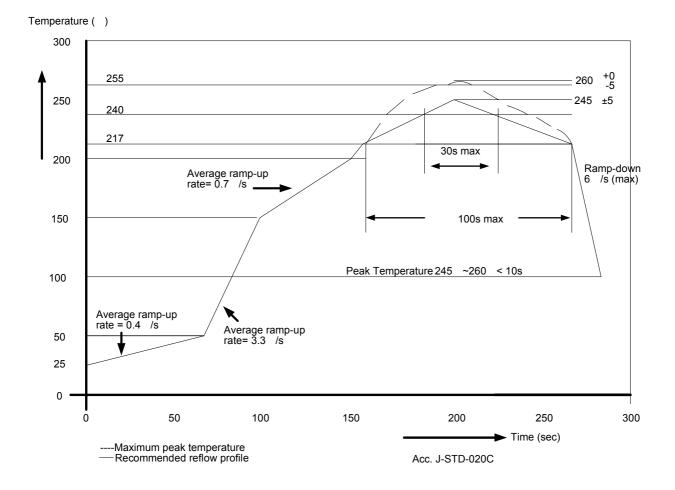
 V_{R-EXT} =1.24V ; I_{OUT} = $V_{R-EXT} x(1/R_{ext})x15$; R_{ext} =(V_{R-EXT}/I_{OUT})x15



Where R_{ext} is the resistance of the external resistor connected to R-EXT terminal and V_{R-EXT} is the voltage of R-EXT terminal. The magnitude of current (as a function of R_{ext}) is around 25mA at 744 Ω and 10mA at 1860 Ω .

Soldering Process of "Pb-free & Green" Package*

Macroblock has defined "Pb-Free & Green" to mean semiconductor products that are compatible with the current RoHS requirements and selected **100% pure tin** (Sn) to provide forward and backward compatibility with both the current industry-standard SnPb-based soldering processes and higher-temperature Pb-free processes. Pure tin is widely accepted by customers and suppliers of electronic devices in Europe, Asia and the US as the lead-free surface finish of choice to replace tin-lead. Also, it is backward compatible to standard 215°C to 240°C reflow processes which adopt tin/lead (SnPb) solder paste. However, in the whole Pb-free soldering processes and materials, 100% pure tin (Sn), will all require up to 260°C for proper soldering on boards, referring to J-STD-020C as shown below.



*Note1: For details, please refer to Macroblock's "Policy on Pb-free & Green Package".

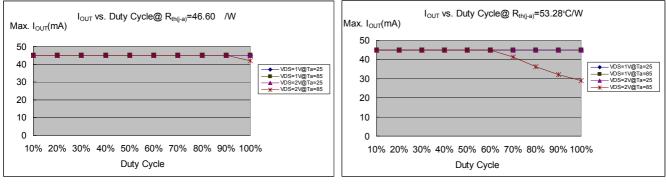
Package Power Dissipation (PD)

The maximum allowable package power dissipation is determined as $P_D(max)=(Tj-Ta)/R_{th(j-a)}$. When 16 output

channels are turned on simultaneously, the actual package power dissipation is

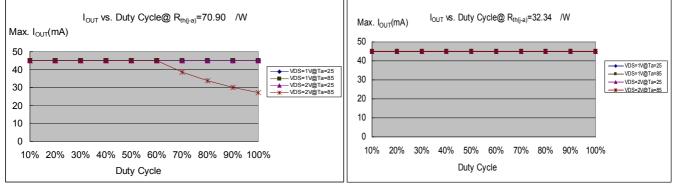
 $P_D(act)=(I_{DD}xV_{DD})+(I_{OUT}xDutyxV_{DS}x16)$. Therefore, to keep $P_D(act) \le P_D(max)$, the allowable maximum output current as a function of duty cycle is:

 $I_{OUT}=\{[(Tj-Ta)/R_{th(j-a)}]-(I_{DD}xV_{DD})\}/V_{DS}/Duty/16$, where Tj=150°C.



MBI5025GD

MBI5025GF

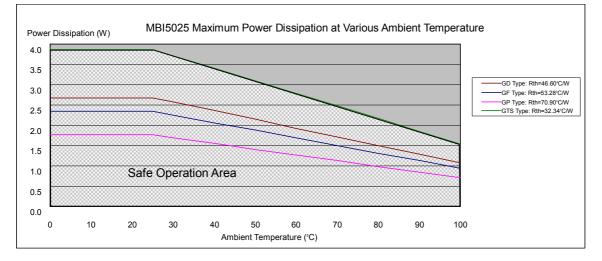


MBI5025GP

MBI5025GTS

Condition: I _{OUT} =45mA,16 output Channels					
Device Type R _{th(j-a)} (°C/W)					
GD	46.60				
GF	53.28				
GP	70.90				
GTS	32.34				

The maximum power dissipation, P_D(max)=(Tj-Ta)/R_{th(j-a)}, decreases as the ambient temperature increases.

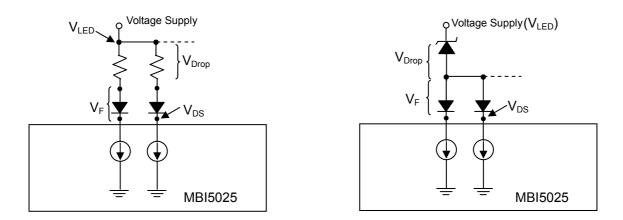


Load Supply Voltage (V_{LED})

MBI5025 are designed to operate with V_{DS} ranging from 0.4V to 0.8V (depending on I_{OUT}=1~45mA) considering the package power dissipating limits. V_{DS} may be higher enough to make $P_{D(act)} > P_{D(max)}$ when V_{LED} =5V and $V_{DS}=V_{LED}-V_{F}$, in which V_{LED} is the load supply voltage. In this case, it is recommended to use the lowest possible supply voltage or to set an external voltage reducer, V_{DROP} .

A voltage reducer lets $V_{DS}=(V_{LED}-V_F)-V_{DROP}$.

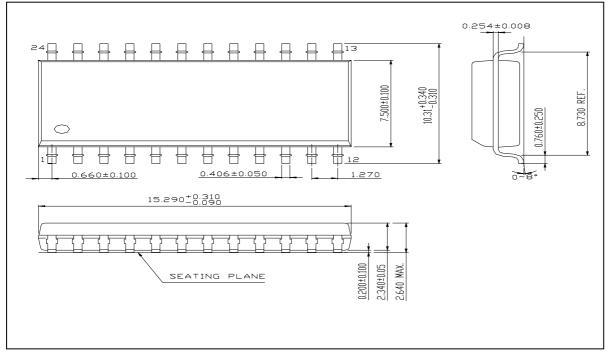
Resistors or Zener diode can be used in the applications as shown in the following figures.



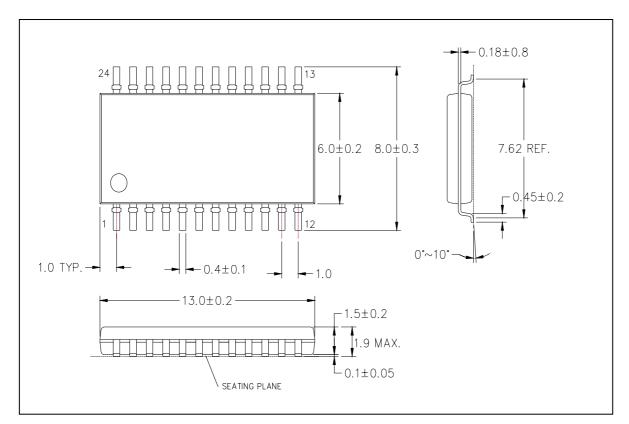
Switching Noise Reduction

LED driver ICs are frequently used in switch-mode applications which always behave with switching noise due to the parasitic inductance on PCB. To eliminate switching noise, refer to "Application Note for 8-bit and 16-bit LED Drivers- Overshoot".

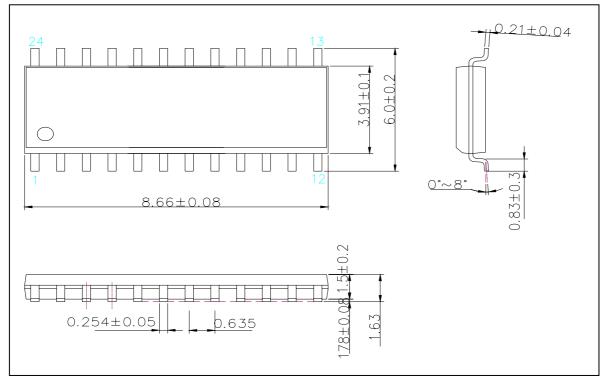
Package Outline



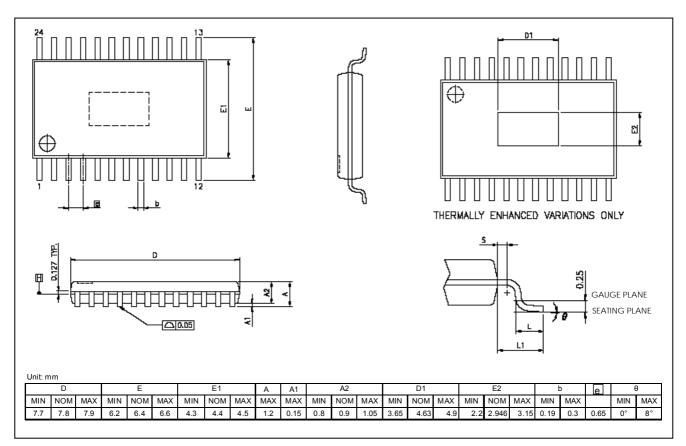
MBI5025GD Outline Drawing



MBI5025GF Outline Drawing



MBI5025GP Outline Drawing

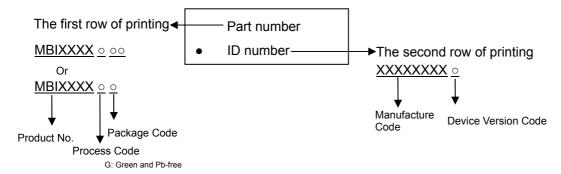


MBI5025GTS Outline Drawing

Note 1: The unit for the outline drawing is mm.

Note 2: Please use the maximum dimensions for the thermal pad layout. To avoid the short circuit risk, the vias or circuit traces shall not pass through the maximum area of thermal pad.

Product Top-mark Information



Product Revision History

Datasheet version	Device version code
V1.00	A
VA.00	A
VA.01	В
VA.02	В
VA.03	В
VA.04	В

Product Ordering Information

Part Number	RoHS Compliant Package Type	Weight (g)
MBI5025GD	SOP24L-300-1.27	0.617
MBI5025GF	SOP24L-300-1.00	0.28
MBI5025GP	SSOP24L-150-0.64	0.11
MBI5025GTS	TSSOP24-173 -0.65	0.0967

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